

# SEMICONDUCTOR DEVICE AND ITS MANUFACTURE

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## Abstract of JP11135712

**PROBLEM TO BE SOLVED:** To provide a package requiring no lead machining, since it has become increasingly difficult to perform the lead machining due to the tendency toward increase in the number of pins. **SOLUTION:** Although signal transmission with the external device of a semiconductor device 2 built into a package 11 is normally made via an external lead, a device has package structure where a function block 8 that has transmission and reception parts in the same package, transmits and receives a signal by radio, and at the same time rectifies the signal as a current source is mounted, thus omitting the external lead of the package 11 and obtaining a semiconductor device without requiring the need for complex lead machining.

